

SBVS024F – NOVEMBER 2000 – REVISED SEPTEMBER 2005

DMOS 250mA Low-Dropout Regulator

FEATURES

- NEW DMOS TOPOLOGY:
 Ultra Low Dropout Voltage:
 150mV typ at 250mA
 Output Capacitor not Required for Stability
- FAST TRANSIENT RESPONSE
- VERY LOW NOISE: 28μVrms
- HIGH ACCURACY: ±1.5% max
- HIGH EFFICIENCY:

 I_{GND} = 600 μ A at I_{OUT} = 250mA Not Enabled: I_{GND} = 0.01 μ A

- 2.5V, 2.8V, 2.85V, 3.0V, 3.3V, AND 5.0V ADJUSTABLE OUTPUT VERSIONS
- OTHER OUTPUT VOLTAGES AVAILABLE UPON REQUEST
- FOLDBACK CURRENT LIMIT
- THERMAL PROTECTION
- SMALL SURFACE-MOUNT PACKAGES: SOT23-5, SOT223-5, and SO-8

APPLICATIONS

- PORTABLE COMMUNICATION DEVICES
- BATTERY-POWERED EQUIPMENT
- PERSONAL DIGITAL ASSISTANTS
- MODEMS
- BAR-CODE SCANNERS
- BACKUP POWER SUPPLIES

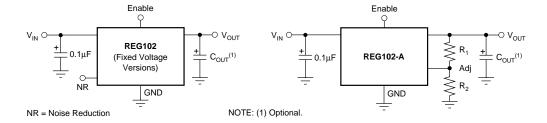
DESCRIPTION

The REG102 is a family of low-noise, low-dropout linear regulators with low ground pin current. The new DMOS topology provides significant improvement over previous designs, including low-dropout voltage (only 150mV typ at full load), and better transient performance. In addition, no output capacitor is required for stability, unlike conventional low-dropout regulators that are difficult to compensate and require expensive low ESR capacitors greater than 1µF.

Typical ground pin current is only $600\mu\text{A}$ (at $I_{\text{OUT}} = 250\text{mA}$) and drops to 10nA when not enabled. Unlike regulators with PNP pass devices, quiescent current remains relatively constant over load variations and under dropout conditions.

The REG102 has very low output noise (typically $28\mu Vrms$ for $V_{OUT}=3.3V$ with $C_{NR}=0.01\mu F$), making it ideal for use in portable communications equipment. On-chip trimming results in high output voltage accuracy. Accuracy is maintained over temperature, line, and load variations. Key parameters are tested over the specified temperature range ($-40^{\circ}C$ to $+85^{\circ}C$).

The REG102 is well protected—internal circuitry provides a current limit that protects the load from damage; furthermore, thermal protection circuitry keeps the chip from being damaged by excessive temperature. The REG102 is available in SOT23-5, SOT223-5, and SO-8 packages.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ABSOLUTE MAXIMUM RATINGS(1)

0.3V to 12V
0.3V to V _{IN}
0.3V to 6.0V
0.3V to 6.0V
Indefinite
–55°C to +125°C
65°C to +150°C
+240°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability.

ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

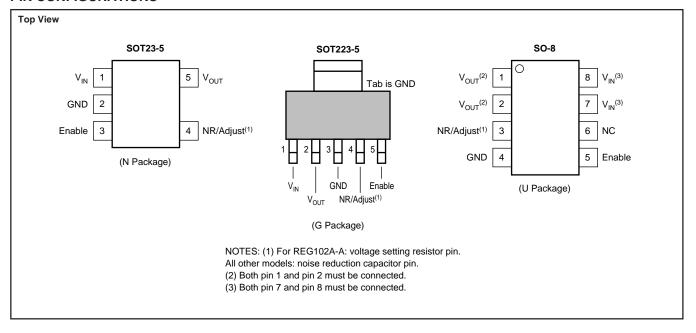
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	V _{OUT} ⁽²⁾
REG102xx-yyyy/zzz	XX is package designator.
	YYYY is typical output voltage (5 = 5.0V, 2.85 = 2.85V, A = Adjustable).
	ZZZ is package quantity.

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (2) Output voltages from 2.5V to 5.1V in 50mV increments are available; minimum order quantities apply. Contact factory for details and availability.

PIN CONFIGURATIONS





ELECTRICAL CHARACTERISTICS

Boldface limits apply over the specified temperature range, $T_J = -40^{\circ}C$ to +85°C.

At T_J = +25°C, V_{IN} = V_{OUT} + 1V (V_{OUT} = 2.5V for REG102-A), V_{ENABLE} = 1.8V, I_{OUT} = 5mA, C_{NR} = 0.01 μ F, and C_{OUT} = 0.1 μ F(1), unless otherwise noted.

				REG102NA REG102GA REG102UA		
PARAMETER		CONDITION	MIN	TYP	MAX	UNITS
OUTPUT VOLTAGE Output Voltage Range REG102-2.5 REG102-2.8 REG102-2.85 REG102-3.0 REG102-3.3 REG102-5 REG102-A Reference Voltage Adjust Pin Current Accuracy Over Temperature vs Temperature	V _{OUT}		2.5	2.5 2.8 2.85 3.0 3.3 5 1.26 0.2 ±0.5	5.5 1 ±1.5 ±2.3	V V V V V V µA % ppm/°C
vs Line and Load		$I_{OUT} = 5mA$ to 250mA, $V_{IN} = (V_{OUT} + 0.4V)$ to 10V		±0.8	±2.0	%
Over Temperature DC DROPOUT VOLTAGE ⁽²⁾ For all models Over Temperature	V_{DROP}	V _{IN} = (V _{OUT} + 0.6V) to 10V I _{OUT} = 5mA I _{OUT} = 250mA I _{OUT} = 250mA		4 150	±2.8 10 220 270	mV mV mV
VOLTAGE NOISE f = 10Hz to 100kHz Without C _{NR} (all models) With C _{NR} (all fixed voltage models)	V _n	$C_{NR} = 0, C_{OUT} = 0$ $C_{NR} = 0.01 \mu F, C_{OUT} = 10 \mu F$	2	 3μVrms/V • V _{OU} - 	 л <u>Г</u>	μVrms μVrms
OUTPUT CURRENT Current Limit(3) Over Temperature Short-Circuit Current Limit	I _{CL}		340 300	400 150	470 490	mA mA mA
RIPPLE REJECTION f = 120Hz				65		dB
ENABLE CONTROL V _{ENABLE} High (output enabled) V _{ENABLE} Low (output disabled) I _{ENABLE} High (output enabled) I _{ENABLE} Low (output disabled) Output Disable Time Output Enable Softstart Time	V _{ENABLE}	$\begin{split} V_{ENABLE} &= 1.8 \text{V to V}_{\text{IN}}, V_{\text{IN}} = 1.8 \text{V to 6.5}^{(4)} \\ V_{ENABLE} &= 0 \text{V to 0.5V} \\ C_{OUT} &= 1.0 \mu \text{F}, R_{LOAD} = 13 \Omega \\ C_{OUT} &= 1.0 \mu \text{F}, R_{LOAD} = 13 \Omega \end{split}$	1.8 -0.2	1 2 50 1.5	V _{IN} 0.5 100 100	V V nA nA μs ms
THERMAL SHUTDOWN Junction Temperature Shutdown Reset from Shutdown				160 140		°C °C
GROUND PIN CURRENT Ground Pin Current Enable Pin Low	I_{GND}	$I_{OUT} = 5mA$ $I_{OUT} = 250mA$ $V_{ENABLE} \le 0.5V$		400 600 0.01	500 800 0.2	μΑ μΑ
INPUT VOLTAGE Operating Input Voltage Range ⁽⁵⁾ Specified Input Voltage Range Over Temperature	V _{IN}	$V_{\text{ENABLE}} \le 0.3V$ $V_{\text{IN}} > 1.8V$ $V_{\text{IN}} > 1.8V$	1.8 V _{OUT} + 0.4 V _{OUT} + 0.6	0.01	10 10 10	μA V V V
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT23-5 Surface-Mount	T _J T _A θ _{JA}	Junction-to-Ambient	-40 -55 -65	200	+85 +125 +150	°C °C °C °C
SO-8 Surface-Mount SOT223-5 Surface-Mount	$egin{array}{l} heta_{\sf JA} \ heta_{\sf JC} \ heta_{\sf JA} \end{array}$	Junction-to-Ambient Junction-to-Case Junction-to-Ambient		150 15 See Figure 8		°C/W °C/W

NOTES: (1) The REG102 does not require a minimum output capacitor for stability, however, transient response can be improved with proper capacitor selection.



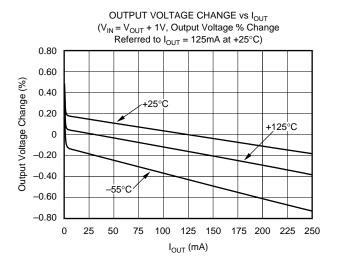
⁽²⁾ Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at V_{IN} = V_{OUT} + 1V at fixed load.

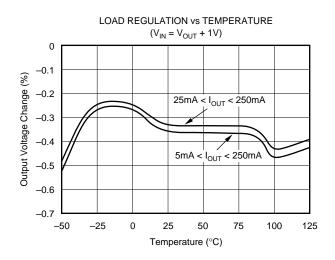
⁽³⁾ Current limit is the output current that produces a 10% change in output voltage from $V_{IN} = V_{OUT} + 1V$ and $I_{OUT} = 5$ mA.

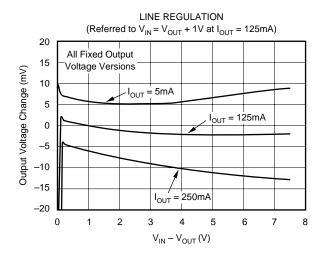
⁽⁴⁾ For $V_{ENABLE} > 6.5V$, see typical characteristic I_{ENABLE} vs V_{ENABLE} .

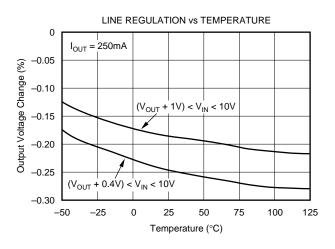
⁽⁵⁾ The REG102 no longer regulates when $V_{IN} < V_{OUT} + V_{DROP~(MAX)}$. In dropout, the impedance from V_{IN} to V_{OUT} is typically less than 1Ω at $T_J = +25^{\circ}C$.

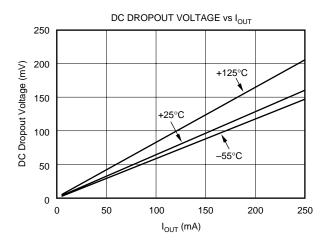
TYPICAL CHARACTERISTICS

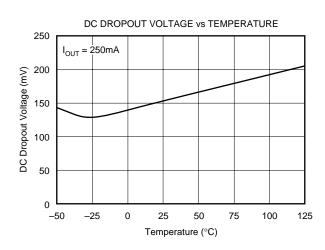


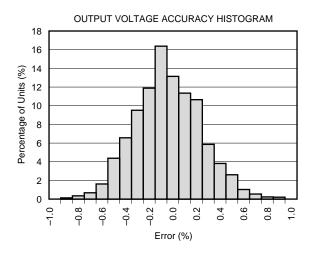


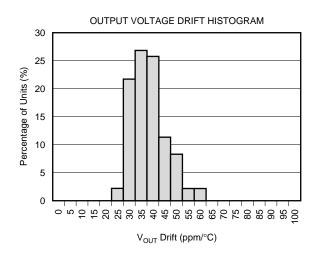


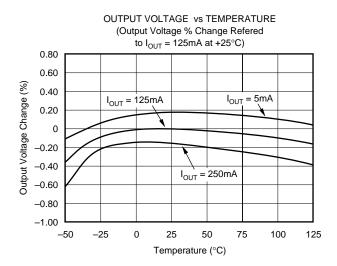


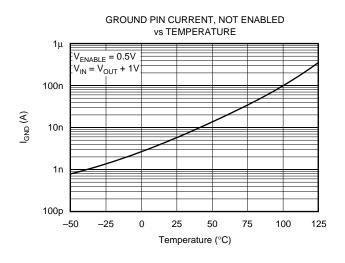


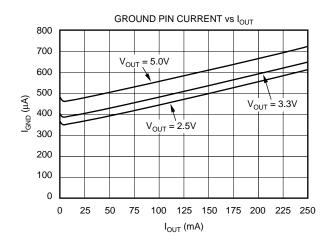


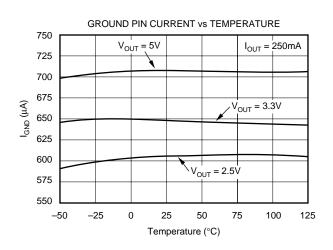




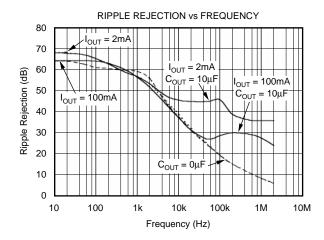


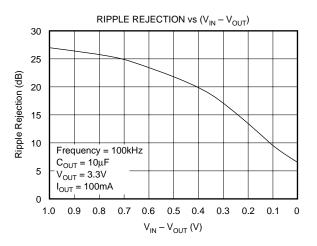


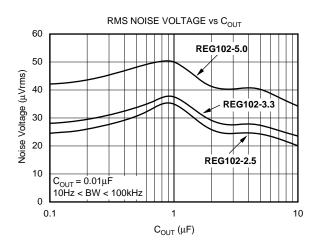


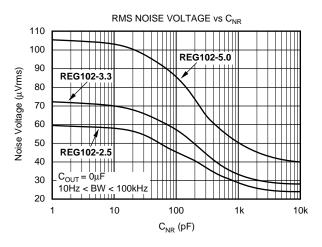


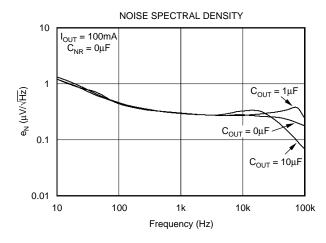


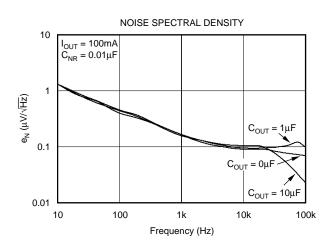




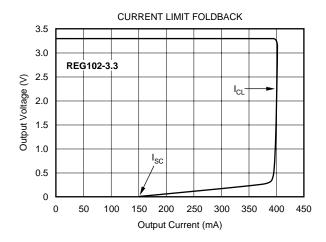


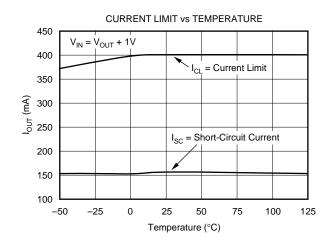


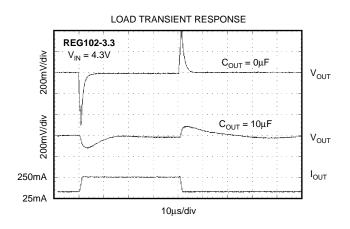


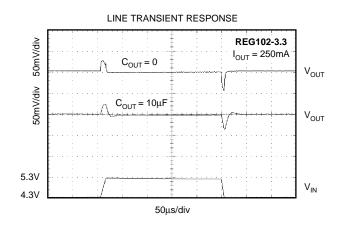


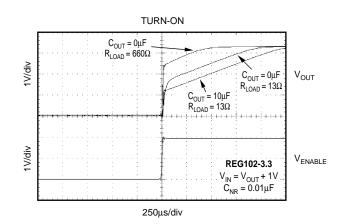


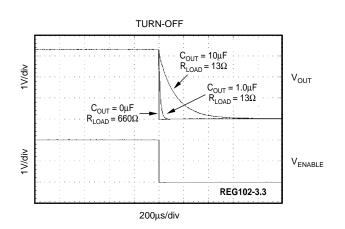






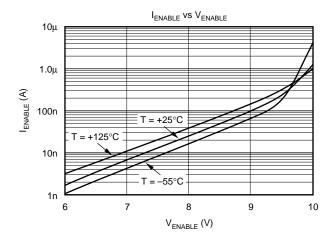


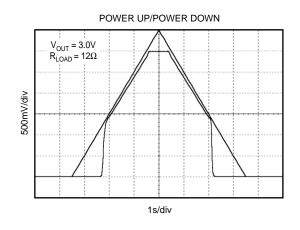


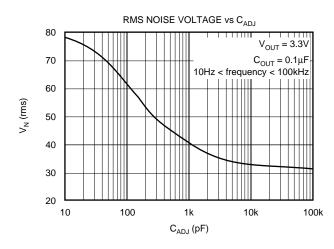


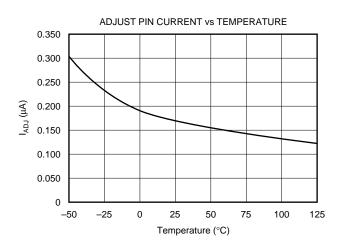


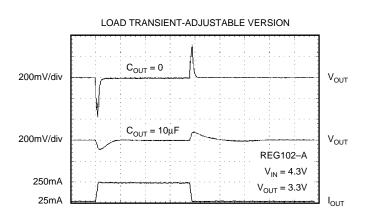


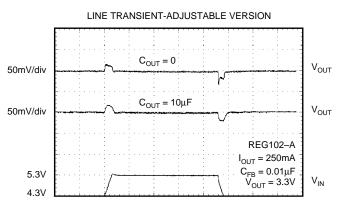














BASIC OPERATION

The REG102 series of LDO (low dropout) linear regulators offers a wide selection of fixed output voltage versions and an adjustable output version as well. The REG102 belongs to a family of new generation LDO regulators that use a DMOS pass transistor to achieve ultra low-dropout performance and freedom from output capacitor constraints. Ground pin current remains under 1mA over all line, load, and temperature conditions. All versions have thermal and overcurrent protection, including foldback current limit.

The REG102 does not require an output capacitor for regulator stability and is stable over most output currents and with almost any value and type of output capacitor up to $10\mu F$ or more. For applications where the regulator output current drops below several milliamps, stability can be enhanced by adding a $1k\Omega$ to $2k\Omega$ load resistor, using capacitance values smaller than $10\mu F$, or keeping the effective series resistance greater than 0.05Ω including the capacitor ESR and parasitic resistance in printed circuit board traces, solder joints, and sockets.

Although an input capacitor is not required, it is a good standard analog design practice to connect a $0.1\mu F$ low ESR capacitor across the input supply voltage. This is recommended to counteract reactive input sources and improve ripple rejection by reducing input voltage ripple.

Figure 1 shows the basic circuit connections for the fixed voltage models. Figure 2 gives the connections for the adjustable output version (REG102A) and example resistor values for some commonly used output voltages. Values for other voltages can be calculated from the equation shown in Figure 2.

INTERNAL CURRENT LIMIT

The REG102 internal current limit has a typical value of 400mA. A foldback feature limits the short-circuit current to a typical short-circuit value of 150mA, which helps to protect

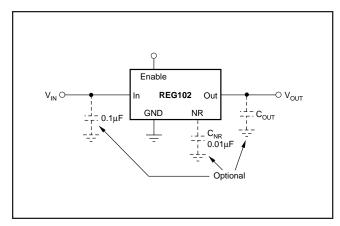


FIGURE 1. Fixed Voltage Nominal Circuit for the REG102.

the regulator from damage under all load conditions. A characteristic of V_{OUT} versus I_{OUT} is given in Figure 3 and in the Typical Characteristics section.

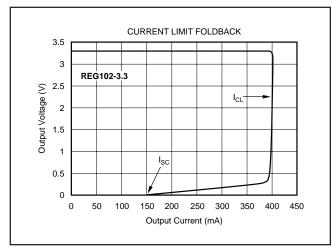


FIGURE 3. Foldback Current Limit of the REG102-3.3 at 25°C.

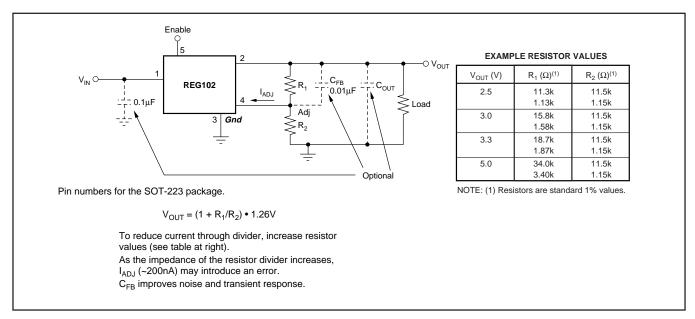


FIGURE 2. Adjustable Voltage Circuit for the REG102A.





ENABLE

The Enable pin is active high and compatible with standard TTL-CMOS levels. Inputs below 0.5V (max) turn the regulator off and all circuitry is disabled. Under this condition, ground pin current drops to approximately 10nA. When not used, the Enable pin can be connected to $V_{\text{IN}}.$ When a pull-up resistor is used, and operation below 1.8V is required, use pull-up resistor values below $50 k\Omega.$

OUTPUT NOISE

A precision bandgap reference is used to generate the internal reference voltage, V_{REF} . This reference is the dominant noise source within the REG102 and generates approximately $29\mu Vrms$ in the 10Hz to 100kHz bandwidth at the reference output. The regulator control loop gains up the reference noise, so that the noise voltage of the regulator is approximately given by:

$$V_{N} = 29\mu V rms \frac{R_{1} + R_{2}}{R2} = 29\mu V rms \bullet \frac{V_{OUT}}{V_{REF}}$$
 (1)

As the value of V_{REF} is 1.26V, this relationship reduces to:

$$V_{N} = 23 \frac{\mu V rms}{V} \bullet V_{OUT}$$
 (2)

Connecting a capacitor, C_{NR} , from the Noise Reduction (NR) pin to ground forms a low-pass filter for the voltage reference. Adding C_{NR} (as shown in Figure 4) forms a low-pass filter for the voltage reference. For $C_{NR} = 10$ nF, the total noise in the 10Hz to 100kHz bandwidth is reduced by approximately a factor of 2.8 for $V_{OUT} = 3.3V$. This noise reduction effect is shown in Figure 5 and as *RMS Noise Voltage vs C_{NR}* in the Typical Characteristics section.

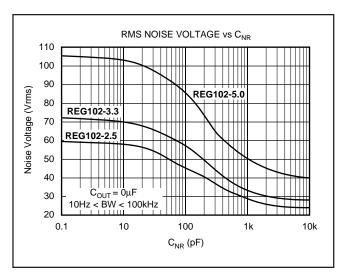


FIGURE 5. Output Noise versus Noise Reduction Capacitor.

Noise can be further reduced by carefully choosing an output capacitor, C_{OUT} . Best overall noise performance is achieved with very low (< 0.22 μ F) or very high (> 2.2 μ F) values of C_{OUT} (see the *RMS Noise Voltage vs C_{OUT}* typical characteristic).

The REG102 uses an internal charge pump to develop an internal supply voltage sufficient to drive the gate of the DMOS pass element above V_{IN} . The charge-pump switching noise (nominal switching frequency = 2MHz) is not measurable at the output of the regulator over most values of I_{OUT} and C_{OUT} .

The REG102 adjustable version does not have the noise-reduction pin available; however, the adjust pin is the summing junction of the error amplifier. A capacitor, C_{FB} , connected from the output to the adjust pin can reduce both the output noise and the peak error from a load transient (see the typical characteristics for output noise performance).

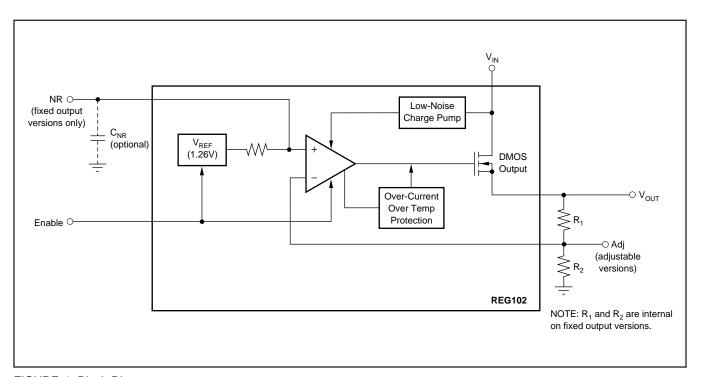


FIGURE 4. Block Diagram.



DROPOUT VOLTAGE

The REG102 uses an N-channel DMOS as the pass element. When $(V_{IN}-V_{OUT})$ is less than the drop-out voltage $(V_{DROP}),$ the DMOS pass device behaves like a resistor; therefore, for low values of $(V_{IN}-V_{OUT}),$ the regulator input-to-output resistance is the Rds_ON of the DMOS pass element (typically 600m Ω). For static (DC) loads, the REG102 typically maintains regulation down to a $(V_{IN}-V_{OUT})$ voltage drop of 150mV at full rated output current. In Figure 6, the bottom line (DC dropout) shows the minimum V_{IN} to V_{OUT} voltage drop required to prevent dropout under DC load conditions.

For large step changes in load current, the REG102 requires a larger voltage drop across it to avoid degraded transient response. The boundary of this transient drop-out region is shown as the top line in Figure 6 and values of $V_{\rm IN}$ to $V_{\rm OUT}$ voltage drop above this line insure normal transient response.

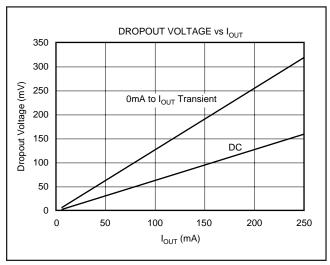


FIGURE 6. Transient and DC Dropout.

In the transient dropout region between DC and Transient, transient response recovery time increases. The time required to recover from a load transient is a function of both the magnitude and rate of the step change in load current and the available headroom V_{IN} to V_{OUT} voltage drop. Under worst-

case conditions (full-scale load change with $(V_{IN}-V_{OUT})$ voltage drop close to DC dropout levels), the REG102 can take several hundred microseconds to re-enter the specified window of regulation.

TRANSIENT RESPONSE

The REG102 response to transient line and load conditions improves at lower output voltages. The addition of a capacitor (nominal value 0.47 μ F) from the output pin to ground can improve the transient response. In the adjustable version, the addition of a capacitor, C_{FB} (nominal value 10nF), from the output to the adjust pin can also improve the transient response.

THERMAL PROTECTION

Power dissipated within the REG102 can cause the junction temperature to rise. The REG102 has thermal shutdown circuitry that protects the regulator from damage which disables the output when the junction temperature reaches approximately 160°C, allowing the device to cool. When the junction temperature cools to approximately 140°C, the output circuitry is again enabled. Depending on various conditions, the thermal protection circuit can cycle on and off. This limits the dissipation of the regulator, but can have an undesirable effect on the load.

Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heat sink. For reliable operation, junction temperature must be limited to 125°C, maximum. To estimate the margin of safety in a complete design (including heat sink), increase the ambient temperature until the thermal protection is triggered; use worst-case loads and signal conditions. For good reliability, thermal protection should trigger more than 35°C above the maximum expected ambient condition of the application. This produces a worst-case junction temperature of 125°C at the highest expected ambient temperature and worst-case load.

The internal protection circuitry of the REG102 is designed to protect against overload conditions and is not intended to replace proper heat sinking. Continuously running the REG102 into thermal shutdown will degrade reliability.





POWER DISSIPATION

The REG102 is available in three different package configurations. The ability to remove heat from the die is different for each package type and, therefore, presents different considerations in the printed circuit board (PCB) layout. The PCB area around the device that is free of other components moves the heat from the device to the ambient air. Although it is difficult to impossible to quantify all of the variables in a thermal design of this type, performance data for several simplified configurations are shown in Figure 7. In all cases, the PCB copper area is bare copper (free of solder resist mask), not solder plated, and are for 1-ounce copper. Using heavier copper will increase the effectiveness in moving the heat from the device. In those examples where there is copper on both sides of the PCB, no connection has been provided between the two sides. The addition of plated through holes will improve the heat sink effectiveness.

Power dissipation depends on input voltage, load conditions, and duty cycle and is equal to the product of the average output current times the voltage across the output element, $V_{\rm IN}$ to $V_{\rm OUT}$ voltage drop.

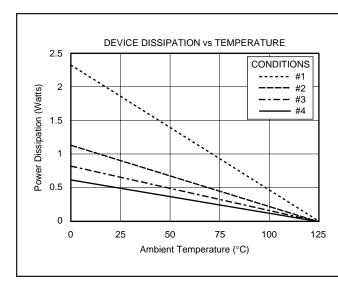
$$P_{D} = (V_{IN} - V_{OUT}) \bullet I_{OUT}$$
 (3)

Power dissipation can be minimized by using the lowest possible input voltage necessary to assure the required output voltage.

REGULATOR MOUNTING

The tab of the SOT-223 package is electrically connected to ground. For best thermal performance, this tab must be soldered directly to a circuit-board copper area. Increasing the copper area improves heat dissipation, as shown in Figure 8.

Although the tab of the SOT-223 is electrical ground, it is not intended to carry current. The copper pad that acts as a heat sink should be isolated from the rest of the circuit to prevent current flow through the device from the tab to the ground pin. Solder pad footprint recommendations for the various REG102 devices are presented in Application Bulletin *Solder Pad Recommendations for Surface-Mount Devices* (SBFA015), available from the Texas Instruments web site (www.ti.com).



CONDITION	PACKAGE	PCB AREA	$ heta_{JA}$		
1	SOT-223	4in2 Top Side Only	53°C/W		
2	SOT-223	0.5in2 Top Side Only	110°C/W		
3	SO-8	_	150°C/W		
4	4 SOT-23 —				

FIGURE 7. Maximum Power Dissipation versus Ambient Temperature for the Various Packages and PCB Heat Sink Configurations.

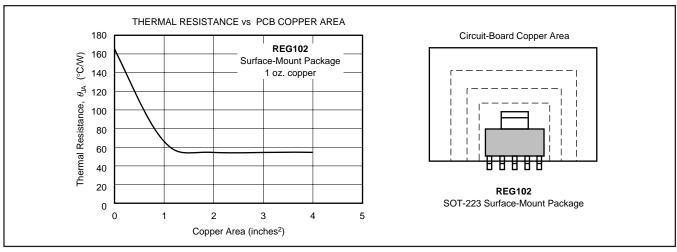


FIGURE 8. Thermal Resistance versus PCB Area for the Five-Lead SOT-223.



7-May-2025



www.ti.com

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	(1)	(2)			(0)	(4)	(5)		(0)
REG102GA-2.5	Obsolete	Production	SOT-223 (DCQ) 6	-	-	Call TI	Call TI	-	R102G25
REG102GA-2.85	Obsolete	Production	SOT-223 (DCQ) 6	-	-	Call TI	Call TI	-	R102285
REG102GA-3	Active	Production	SOT-223 (DCQ) 6	78 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	R102G30
REG102GA-3.3	Active	Production	SOT-223 (DCQ) 6	78 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	R102G33
REG102GA-3.3/2K5	Active	Production	SOT-223 (DCQ) 6	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	R102G33
REG102GA-5	Active	Production	SOT-223 (DCQ) 6	78 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	R102G50
REG102GA-A	Active	Production	SOT-223 (DCQ) 6	78 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-	R102GA
REG102GA-A/2K5	Active	Production	SOT-223 (DCQ) 6	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-	R102GA
REG102NA-2.5/250	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-	RO2D
REG102NA-2.8/250	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-	RO2E
REG102NA-2.85/250	Obsolete	Production	SOT-23 (DBV) 5	-	-	Call TI	Call TI	-	RO2N
REG102NA-2.85/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	RO2N
REG102NA-3.3/250	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2C
REG102NA-3.3/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2C
REG102NA-3/250	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2G
REG102NA-3/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2G
REG102NA-5/250	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2B
REG102NA-5/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	RO2B
REG102NA-A/250	Active	Production	SOT-23 (DBV) 5	250 SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	RO2A
REG102NA-A/3K	Active	Production	SOT-23 (DBV) 5	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	RO2A
REG102UA-2.5	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-	REG 102U25
REG102UA-3	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	REG 102U30
REG102UA-3.3	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	REG 102U33
REG102UA-3.3/2K5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	REG 102U33
REG102UA-5	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	REG 102U50



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Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
REG102UA-5/2K5	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	REG 102U50

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



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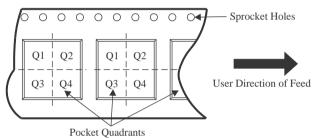
TAPE AND REEL INFORMATION



TAPE DIMENSIONS WHO WE PI AD BO W Cavity AO A

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REG102GA-3.3/2K5	SOT-223	DCQ	6	2500	330.0	12.4	7.1	7.45	1.88	8.0	12.0	Q3
REG102GA-A/2K5	SOT-223	DCQ	6	2500	330.0	12.4	7.1	7.45	1.88	8.0	12.0	Q3
REG102NA-2.85/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-2.85/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-3.3/250	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-3.3/250	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-3.3/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-3.3/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-3/250	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-3/250	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-3/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-3/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-5/250	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
REG102NA-5/250	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-5/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-5/3K	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3



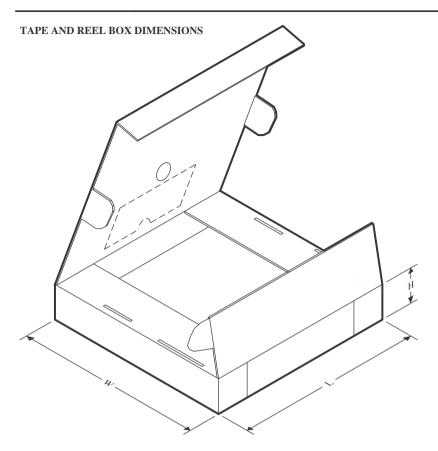
PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
REG102NA-A/250	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102NA-A/3K	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
REG102UA-3.3/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
REG102UA-5/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REG102GA-3.3/2K5	SOT-223	DCQ	6	2500	346.0	346.0	29.0
REG102GA-A/2K5	SOT-223	DCQ	6	2500	346.0	346.0	29.0
REG102NA-2.85/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
REG102NA-2.85/3K	SOT-23	DBV	5	3000	200.0	183.0	25.0
REG102NA-3.3/250	SOT-23	DBV	5	250	180.0	180.0	18.0
REG102NA-3.3/250	SOT-23	DBV	5	250	200.0	183.0	25.0
REG102NA-3.3/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
REG102NA-3.3/3K	SOT-23	DBV	5	3000	200.0	183.0	25.0
REG102NA-3/250	SOT-23	DBV	5	250	203.0	203.0	35.0
REG102NA-3/250	SOT-23	DBV	5	250	180.0	180.0	18.0
REG102NA-3/3K	SOT-23	DBV	5	3000	200.0	183.0	25.0
REG102NA-3/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
REG102NA-5/250	SOT-23	DBV	5	250	180.0	180.0	18.0
REG102NA-5/250	SOT-23	DBV	5	250	200.0	183.0	25.0
REG102NA-5/3K	SOT-23	DBV	5	3000	200.0	183.0	25.0
REG102NA-5/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0
REG102NA-A/250	SOT-23	DBV	5	250	200.0	183.0	25.0
REG102NA-A/3K	SOT-23	DBV	5	3000	203.0	203.0	35.0



PACKAGE MATERIALS INFORMATION

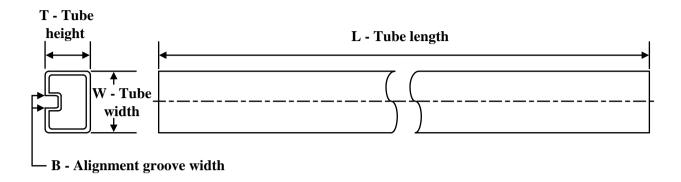
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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
REG102UA-3.3/2K5	SOIC	D	8	2500	356.0	356.0	35.0
REG102UA-5/2K5	SOIC	D	8	2500	356.0	356.0	35.0



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TUBE

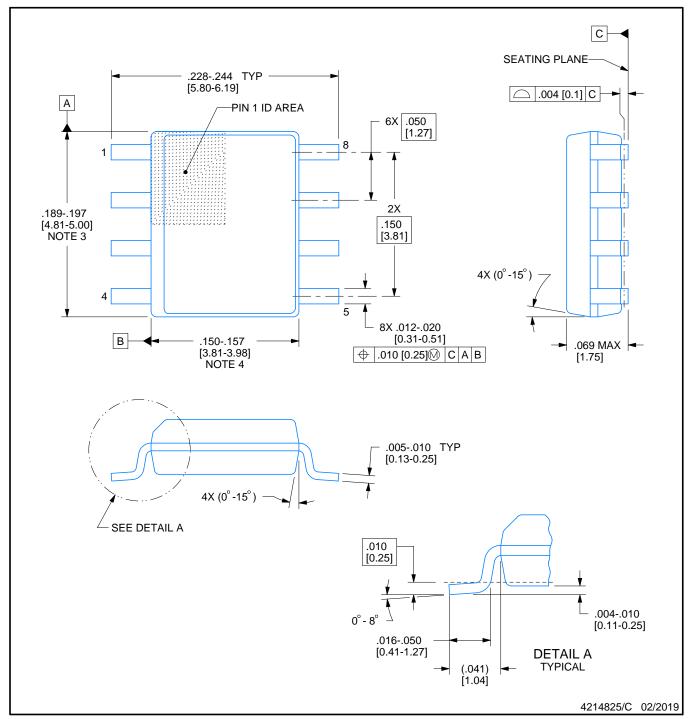


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
REG102GA-3	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102GA-3.3	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102GA-3.3G4	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102GA-5	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102GA-A	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102GA-AG4	DCQ	SOT-223	6	78	532.13	8.63	3.6	3.68
REG102UA-3	D	SOIC	8	75	506.6	8	3940	4.32
REG102UA-3.3	D	SOIC	8	75	506.6	8	3940	4.32
REG102UA-5	D	SOIC	8	75	506.6	8	3940	4.32
REG102UA-5G4	D	SOIC	8	75	506.6	8	3940	4.32



SMALL OUTLINE INTEGRATED CIRCUIT

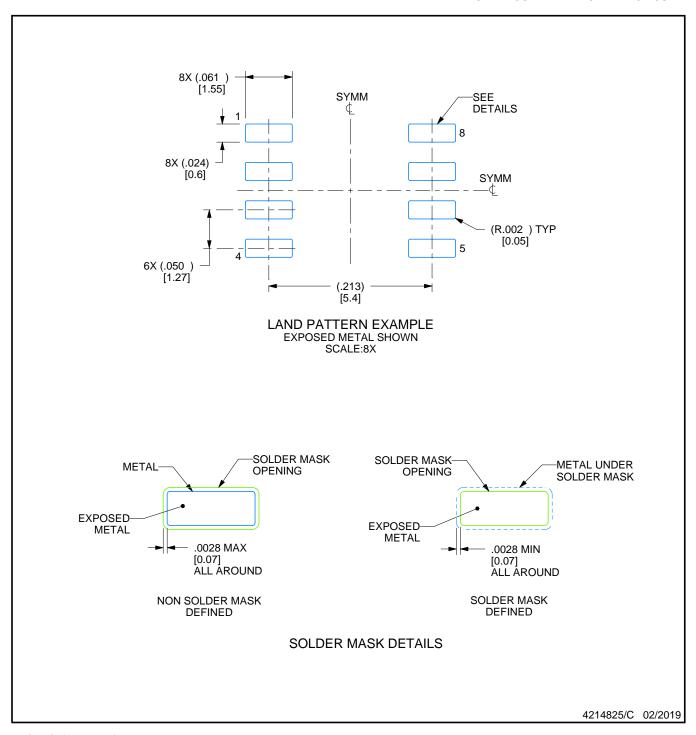


NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT

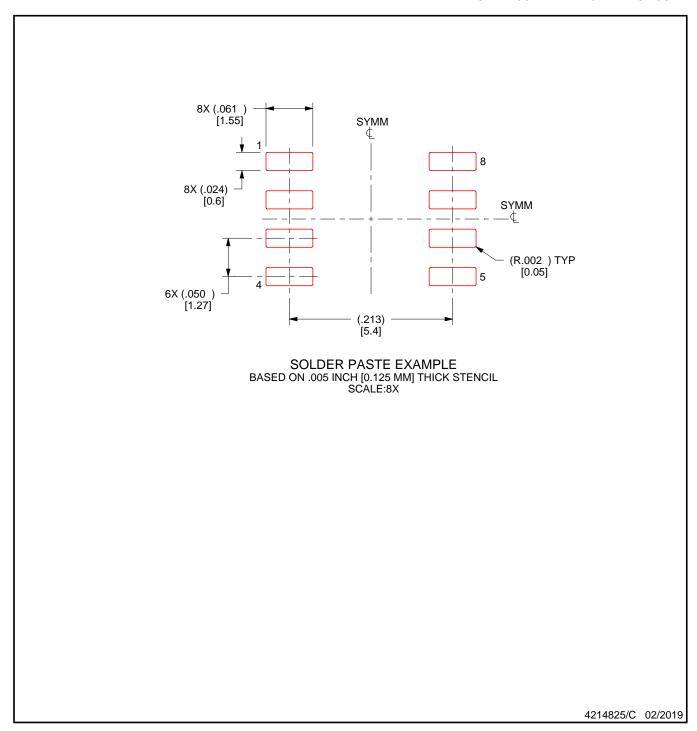


NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE INTEGRATED CIRCUIT



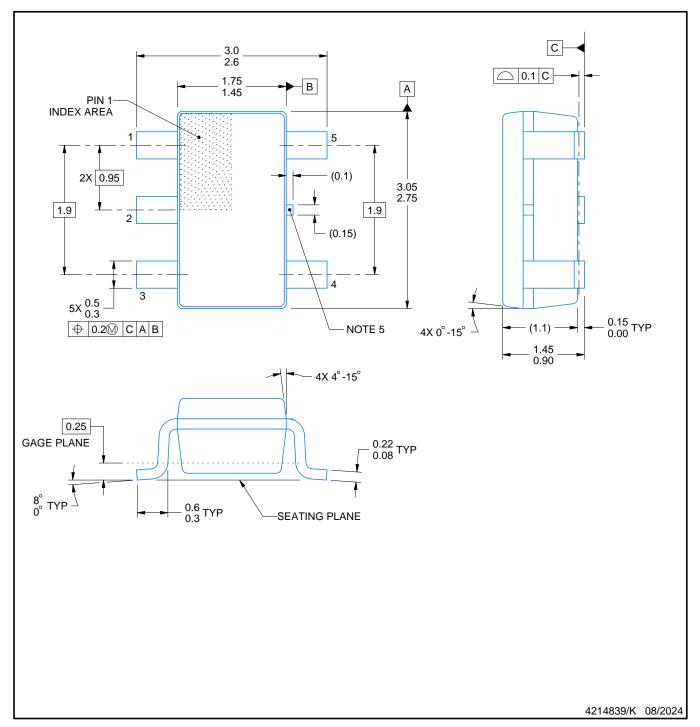
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





SMALL OUTLINE TRANSISTOR



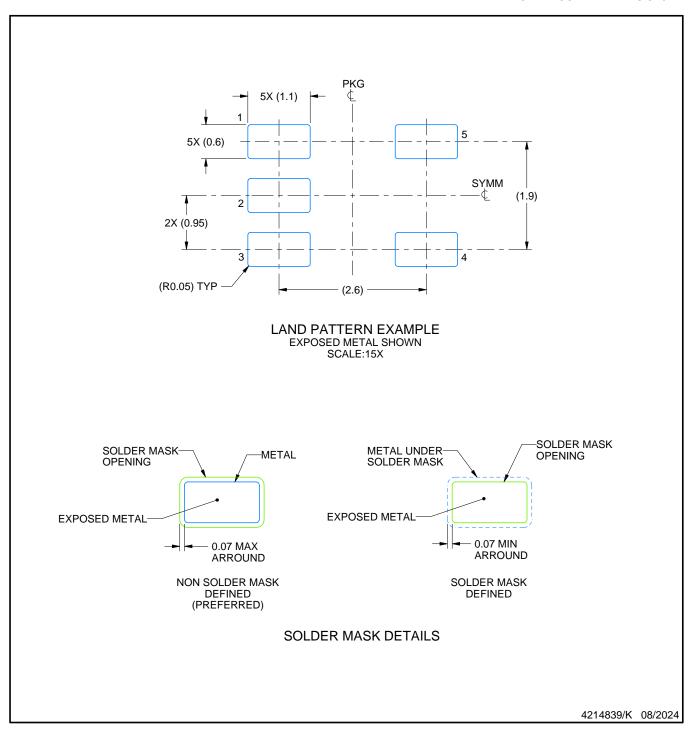
NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



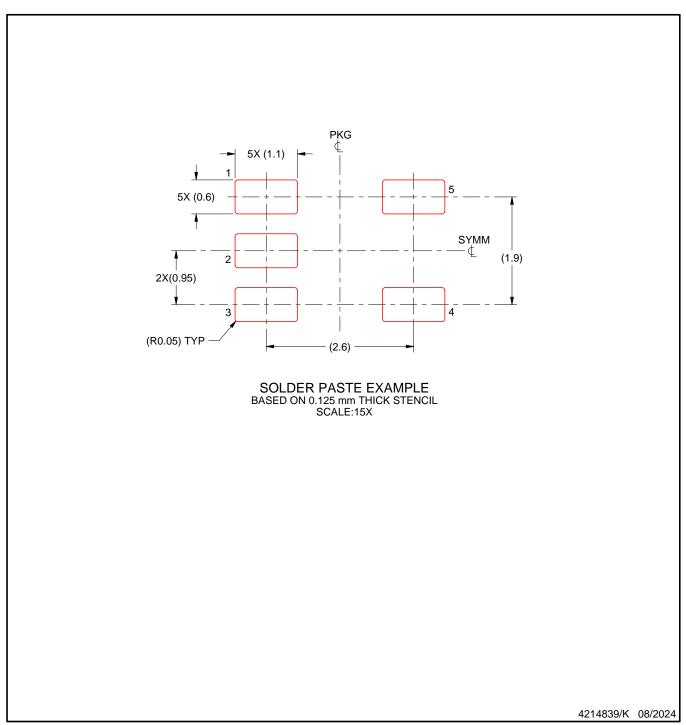
SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

SMALL OUTLINE TRANSISTOR



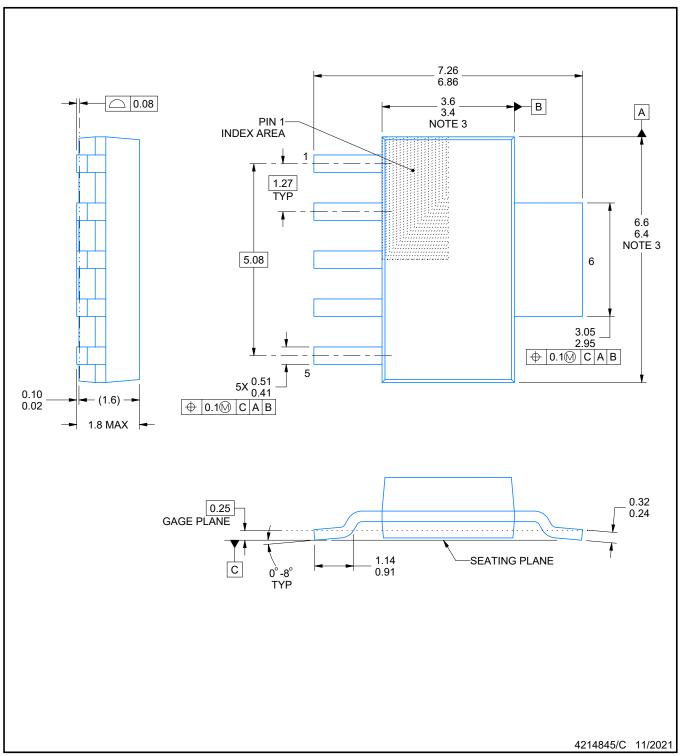
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.





PLASTIC SMALL OUTLINE



NOTES:

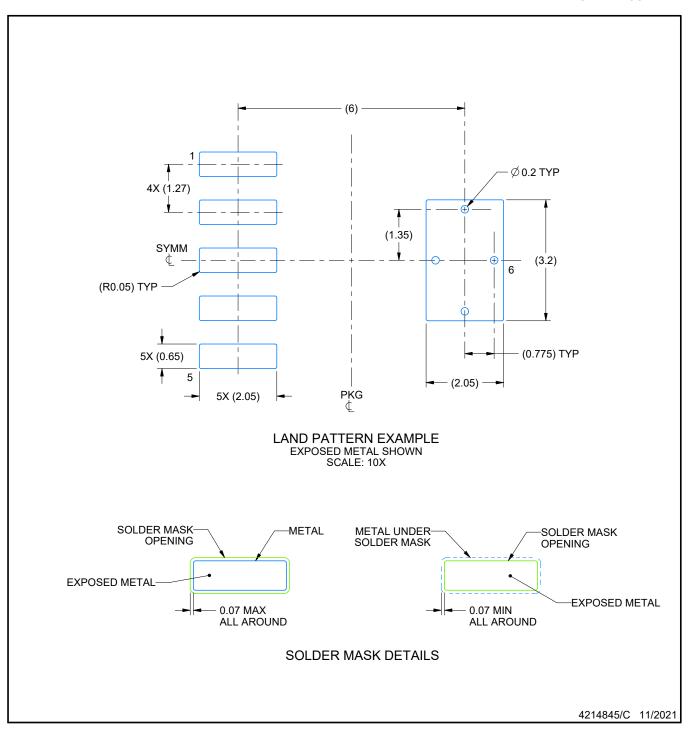
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.



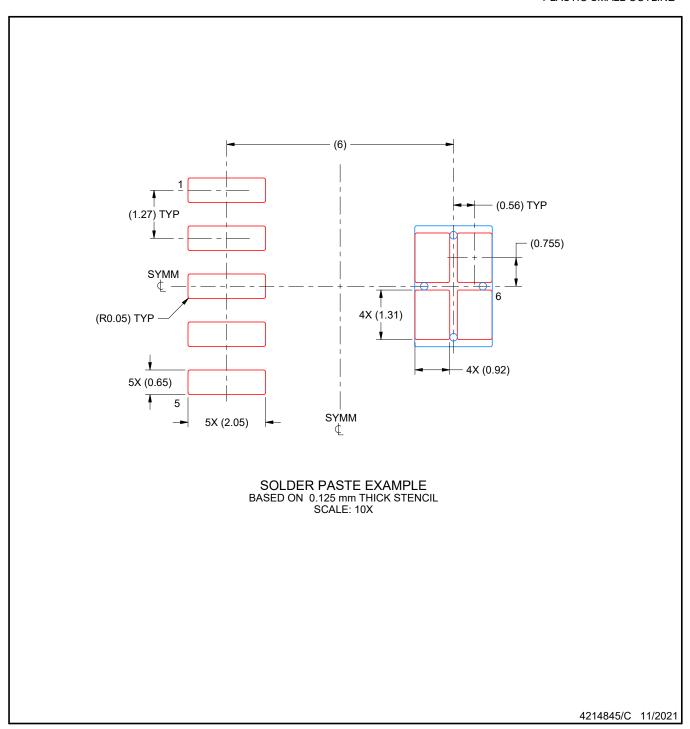
PLASTIC SMALL OUTLINE



NOTES: (continued)

- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

PLASTIC SMALL OUTLINE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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